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(12) **United States Design Patent**
Sharma et al.

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(54) **DIAMOND-SHAPED SEMICONDUCTOR DIE**

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(**) Term: **14 Years**

(21) Appl. No.: **29/441,960**

(22) Filed: **Jan. 11, 2013**

Related U.S. Application Data

(63) Continuation of application No. 13/357,578, filed on Jan. 24, 2012, which is a continuation-in-part of application No. 13/163,482, filed on Jun. 17, 2011, now Pat. No. 8,293,551.

(51) **LOC (10) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**

USPC D13/110, 182, 184; 361/679.01, 728,
361/761, 820, 718, 764, 748, 752, 783;
257/668, 678, 684; 324/71.5, 252;
29/825, 829, 830, 831, 832, 846;
174/68.1, 250-261, 268; 216/13;
428/901

See application file for complete search history.

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(57) **CLAIM**

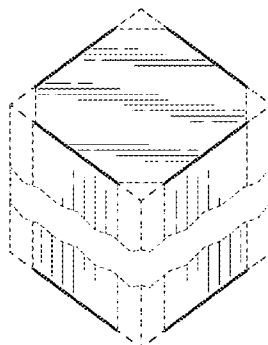
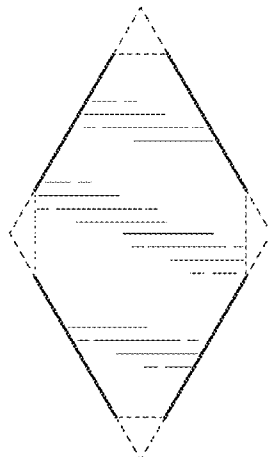
The ornamental design for a diamond-shaped semiconductor die, as shown and described.

DESCRIPTION

FIG. 1 is a top plan view of a first embodiment of a diamond-shaped semiconductor die showing our new design; FIG. 2 is a front perspective view thereof; FIG. 3 is a rear perspective view thereof; FIG. 4 is a top plan view of a second embodiment of a diamond-shaped semiconductor die showing our new design; FIG. 5 is a front perspective view thereof; FIG. 6 is a rear perspective view thereof; FIG. 7 is a top plan view of a third embodiment of a diamond-shaped semiconductor die showing our new design; FIG. 8 is a front perspective view thereof; FIG. 9 is a rear perspective view thereof; FIG. 10 is a top plan view of a fourth embodiment of a diamond-shaped semiconductor die showing our new design; FIG. 11 is a front perspective view thereof; FIG. 12 is a rear perspective view thereof; FIG. 13 is a top plan view of a fifth embodiment of a diamond-shaped semiconductor die showing our new design; FIG. 14 is a front perspective view thereof; FIG. 15 is a rear perspective view thereof; FIG. 16 is a top plan view of a sixth embodiment of a diamond-shaped semiconductor die showing our new design; FIG. 17 is a front perspective view thereof; and, FIG. 18 is a rear perspective view thereof.

The broken lines in the figures represent unclaimed subject matter and form no part of the claimed design. The diamond-shaped semiconductor die is shown broken away in FIGS. 1-18 to indicate that no particular length is claimed.

1 Claim, 16 Drawing Sheets



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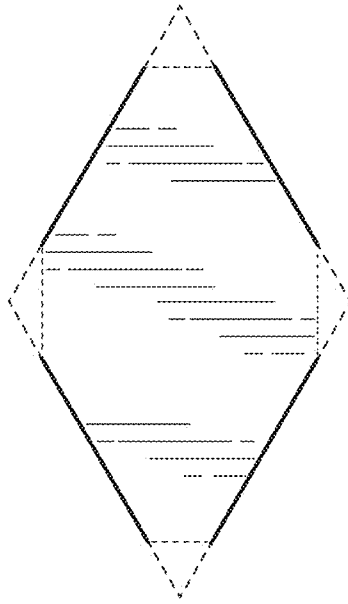


FIG. 1

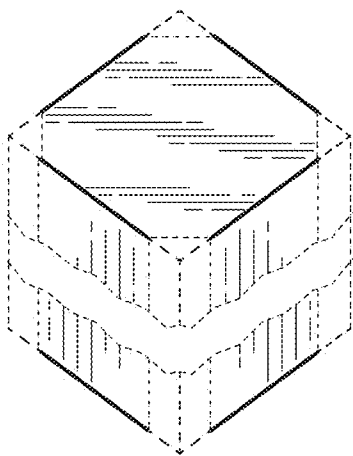


FIG. 2

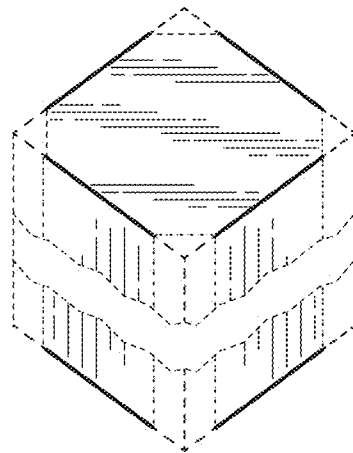


FIG. 3

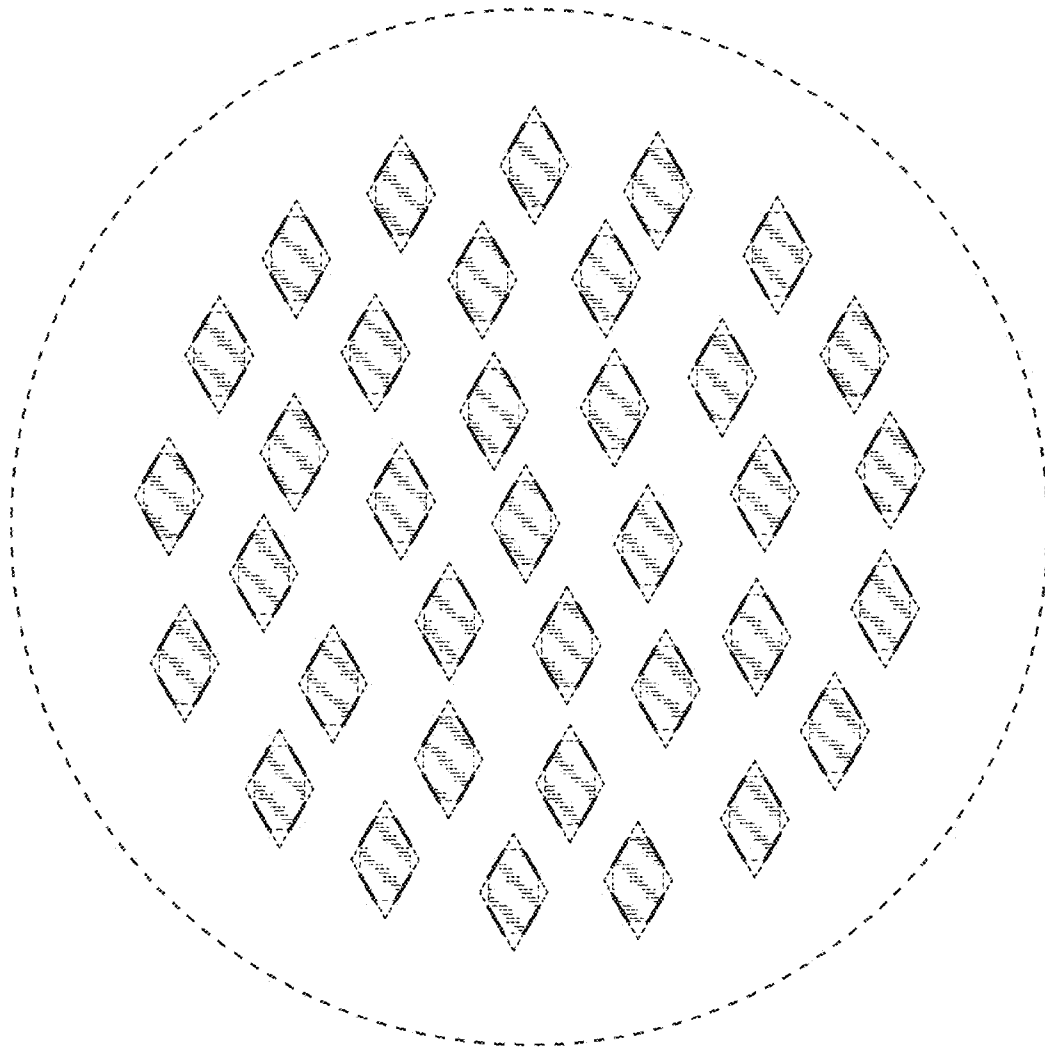


FIG. 4

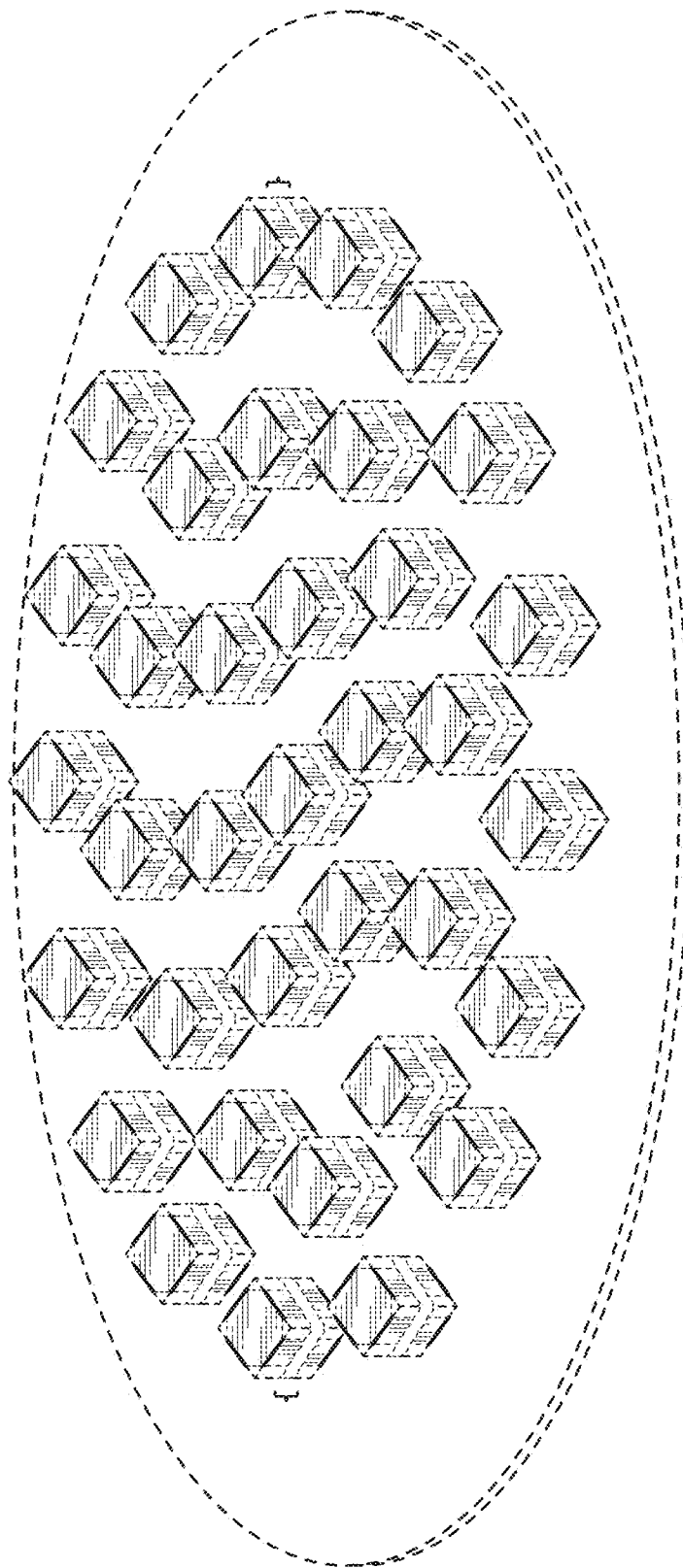


FIG. 5

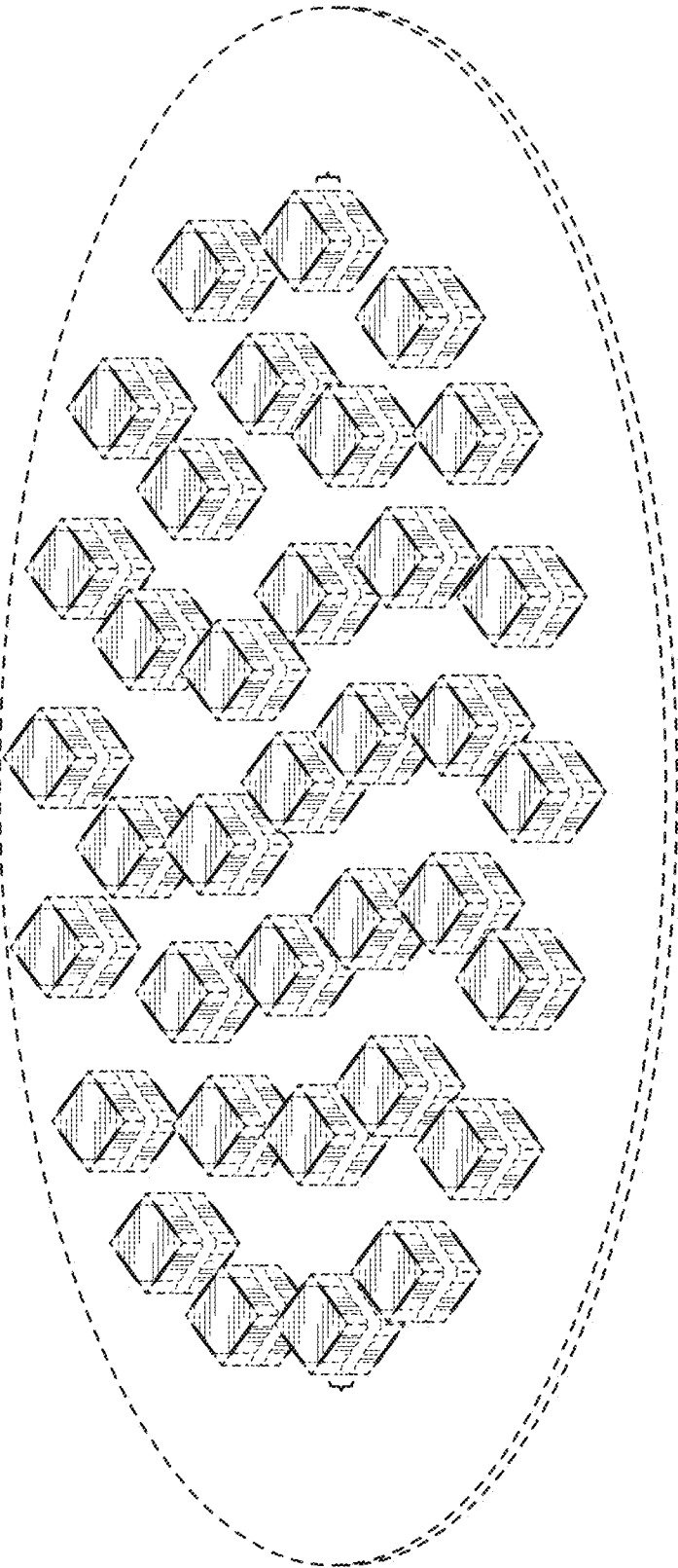


FIG. 6

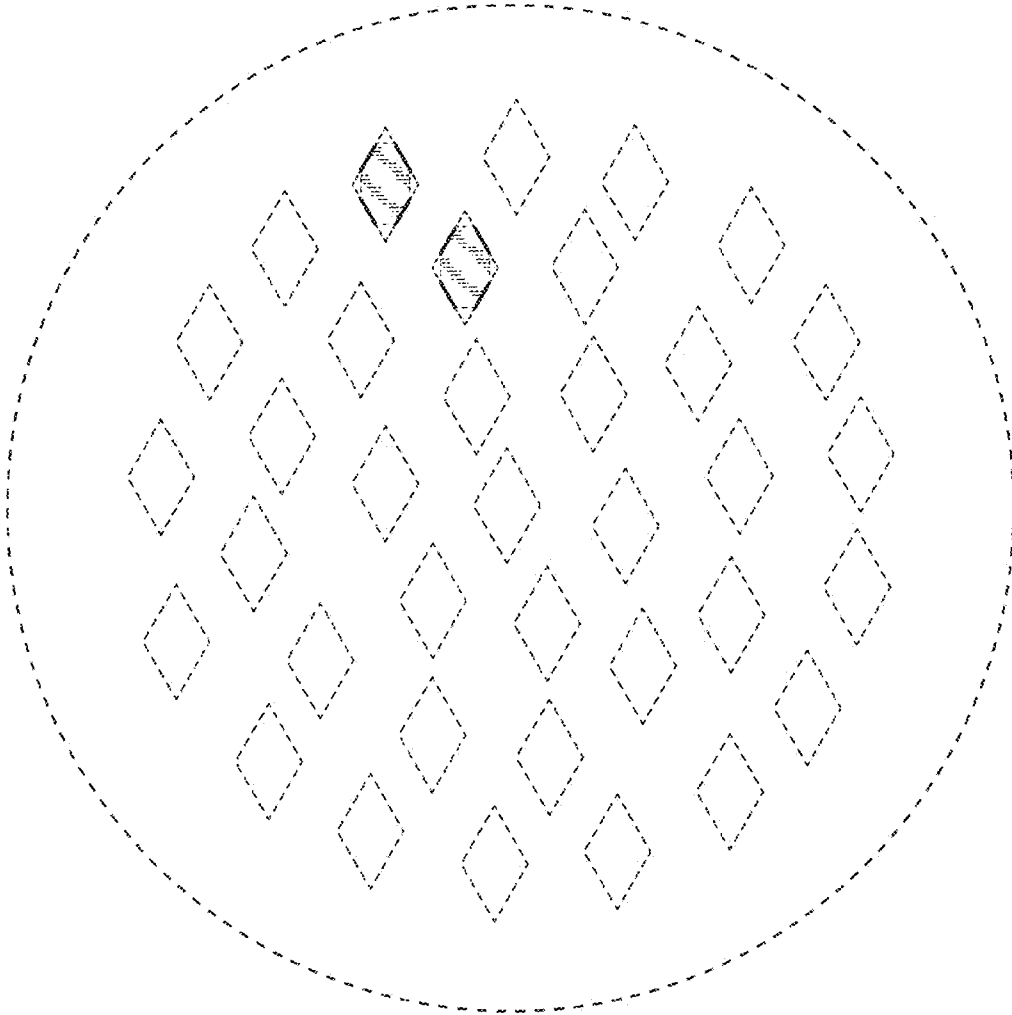


FIG. 7

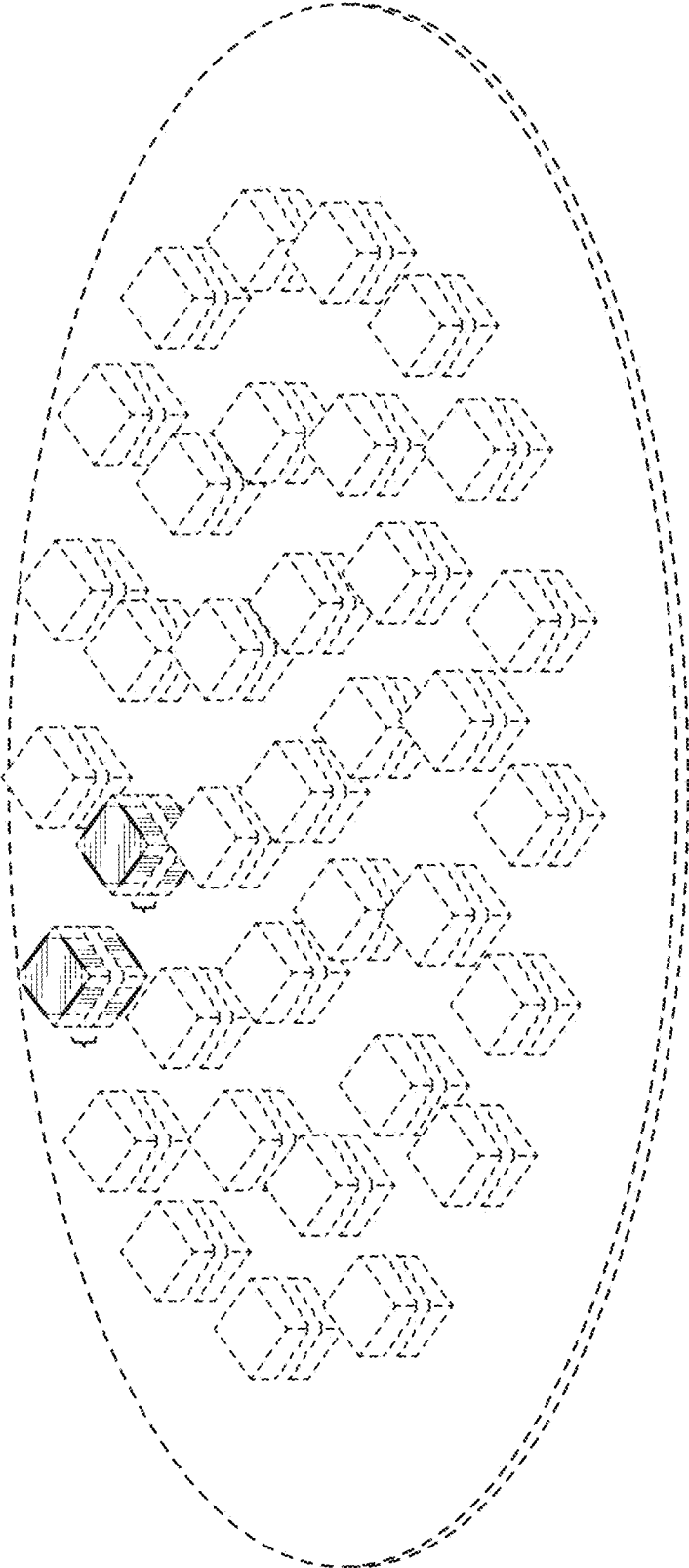


FIG. 8

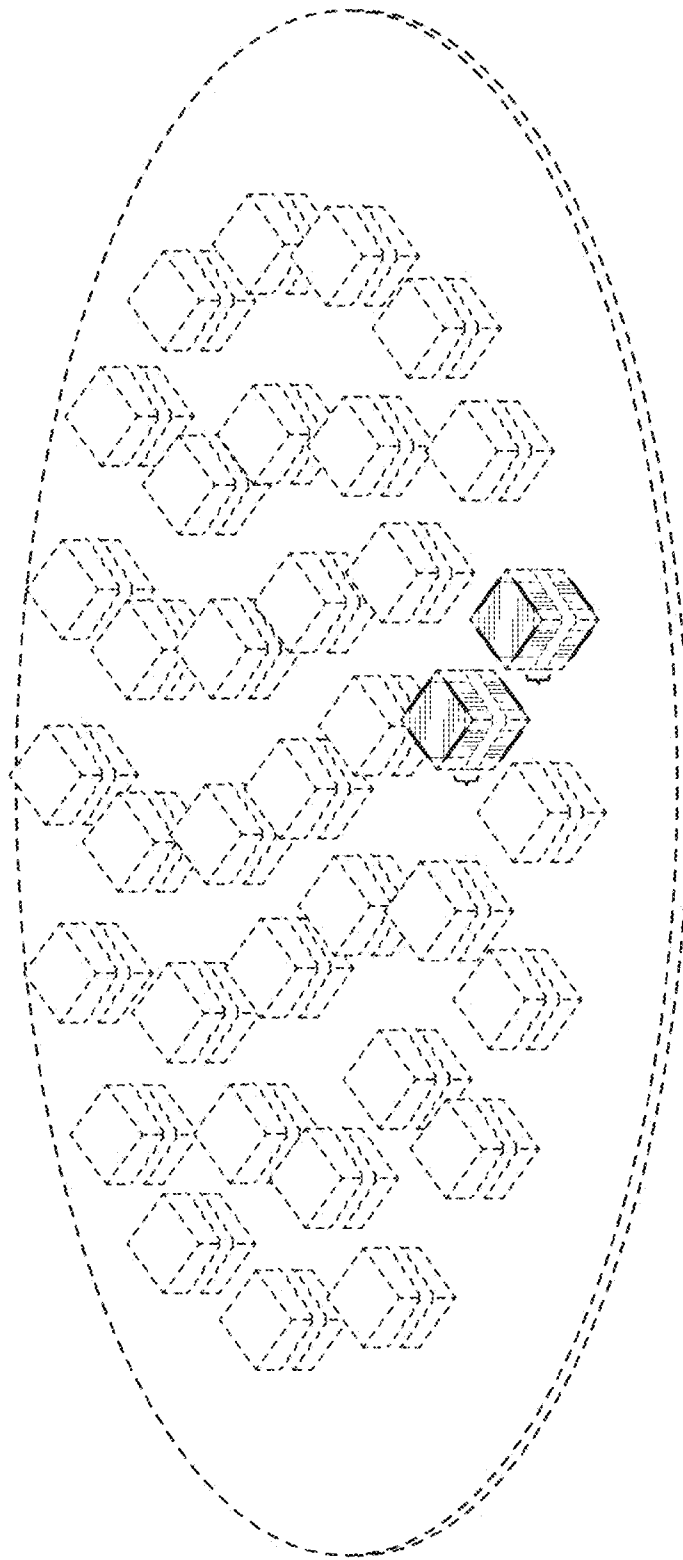


FIG. 9

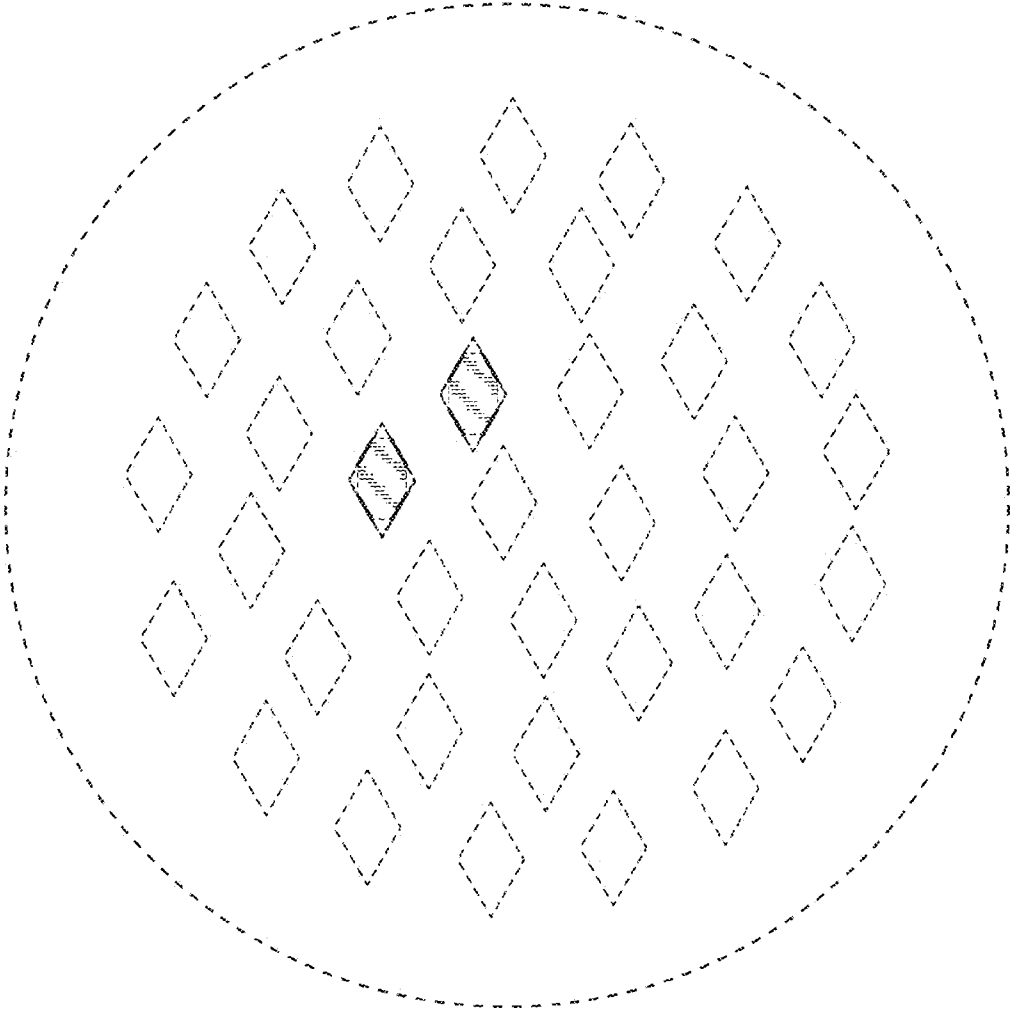


FIG. 10

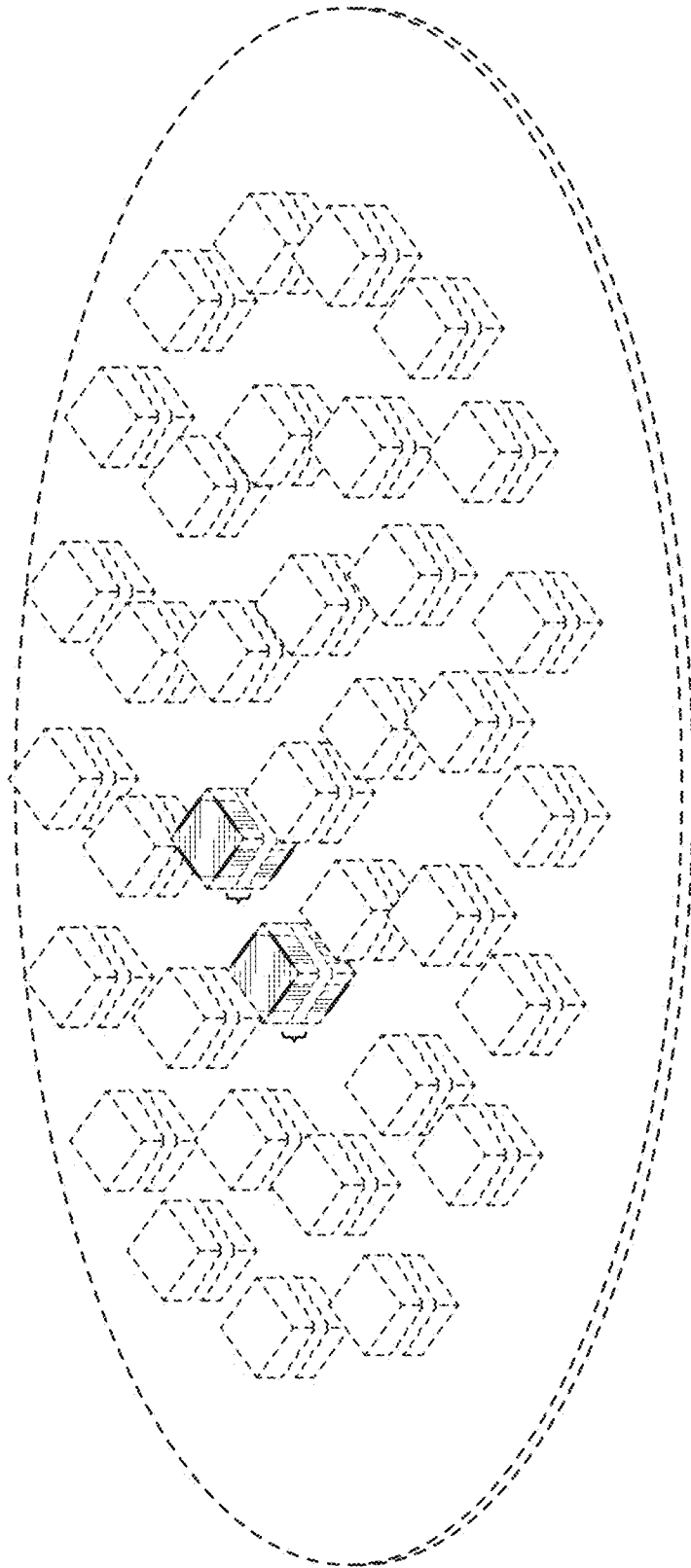


FIG. 11

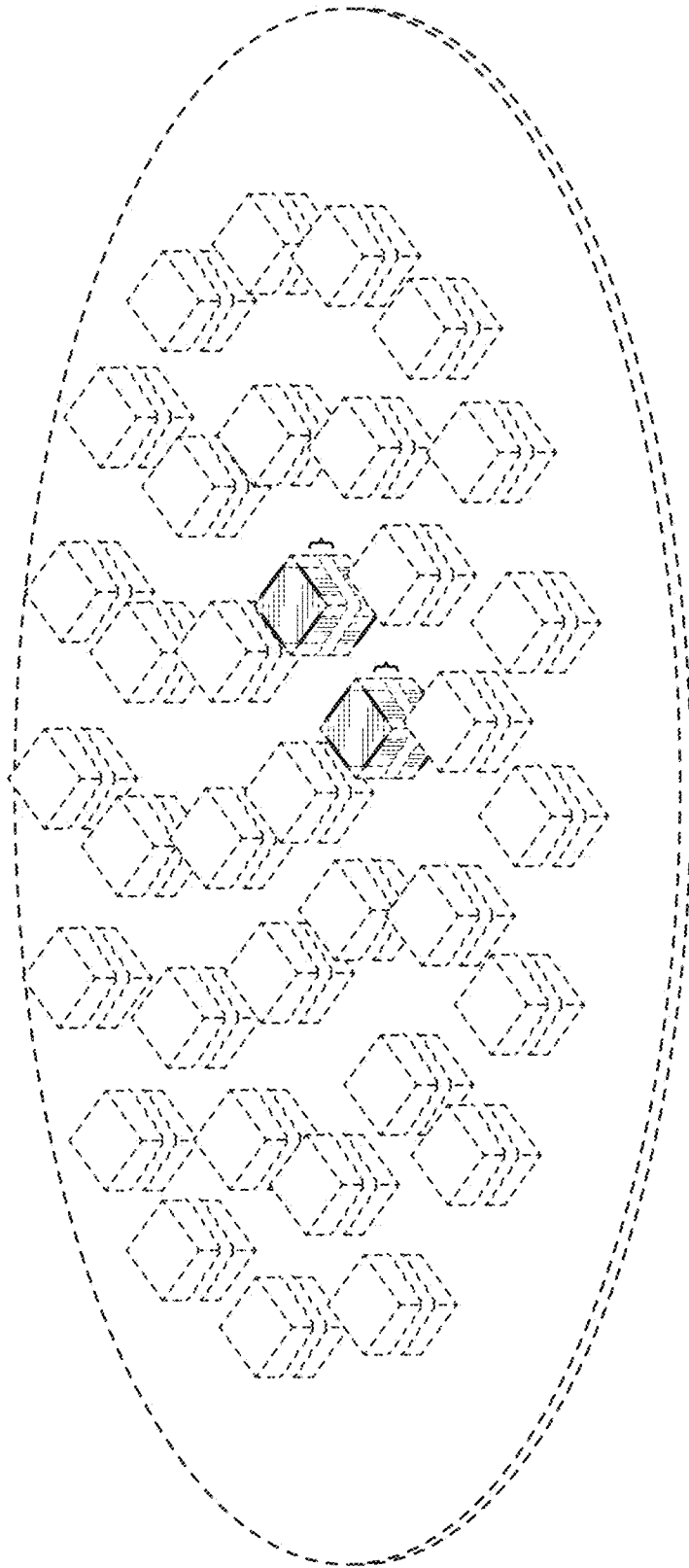


FIG. 12

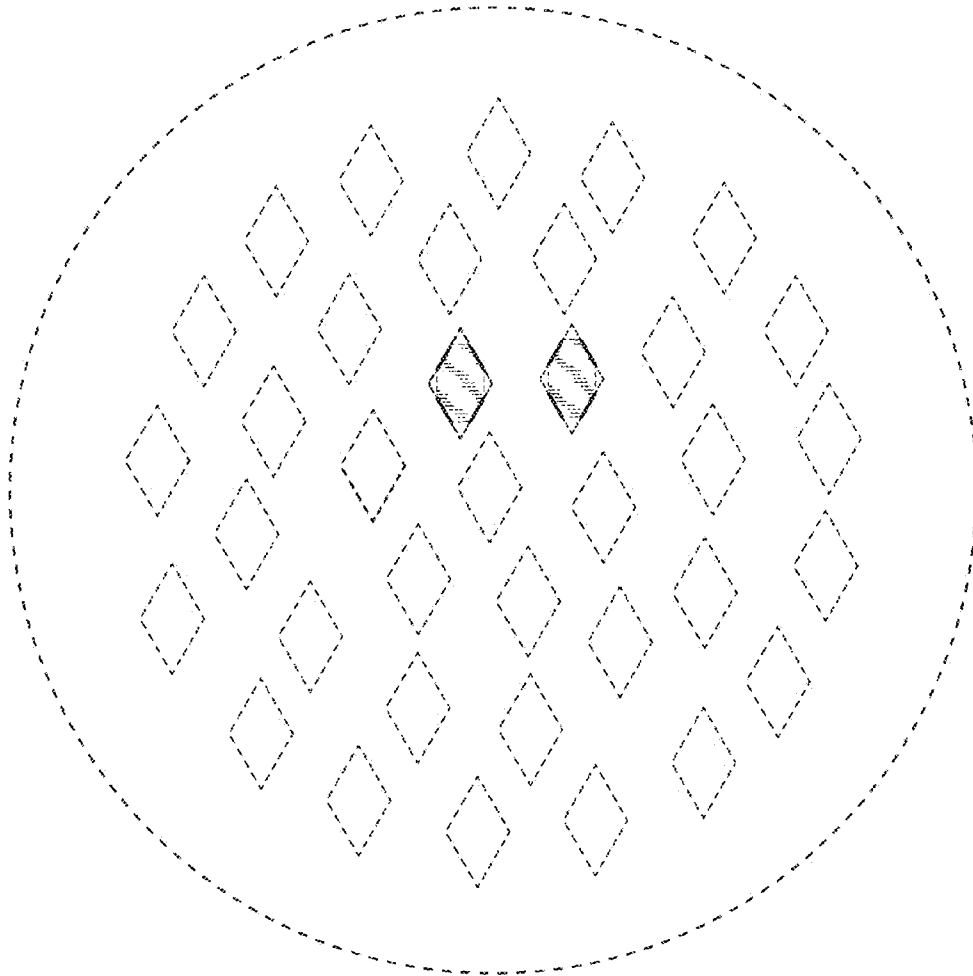


FIG. 13

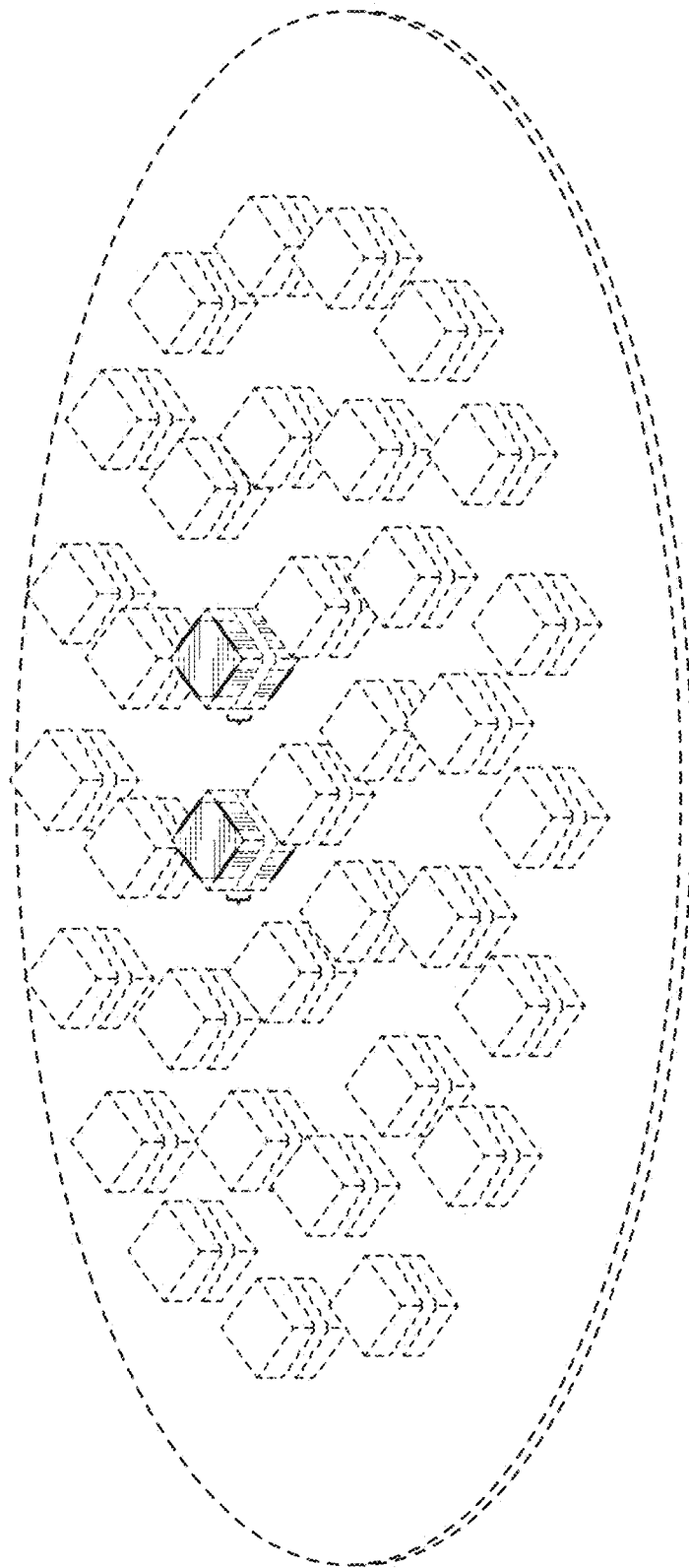


FIG. 14

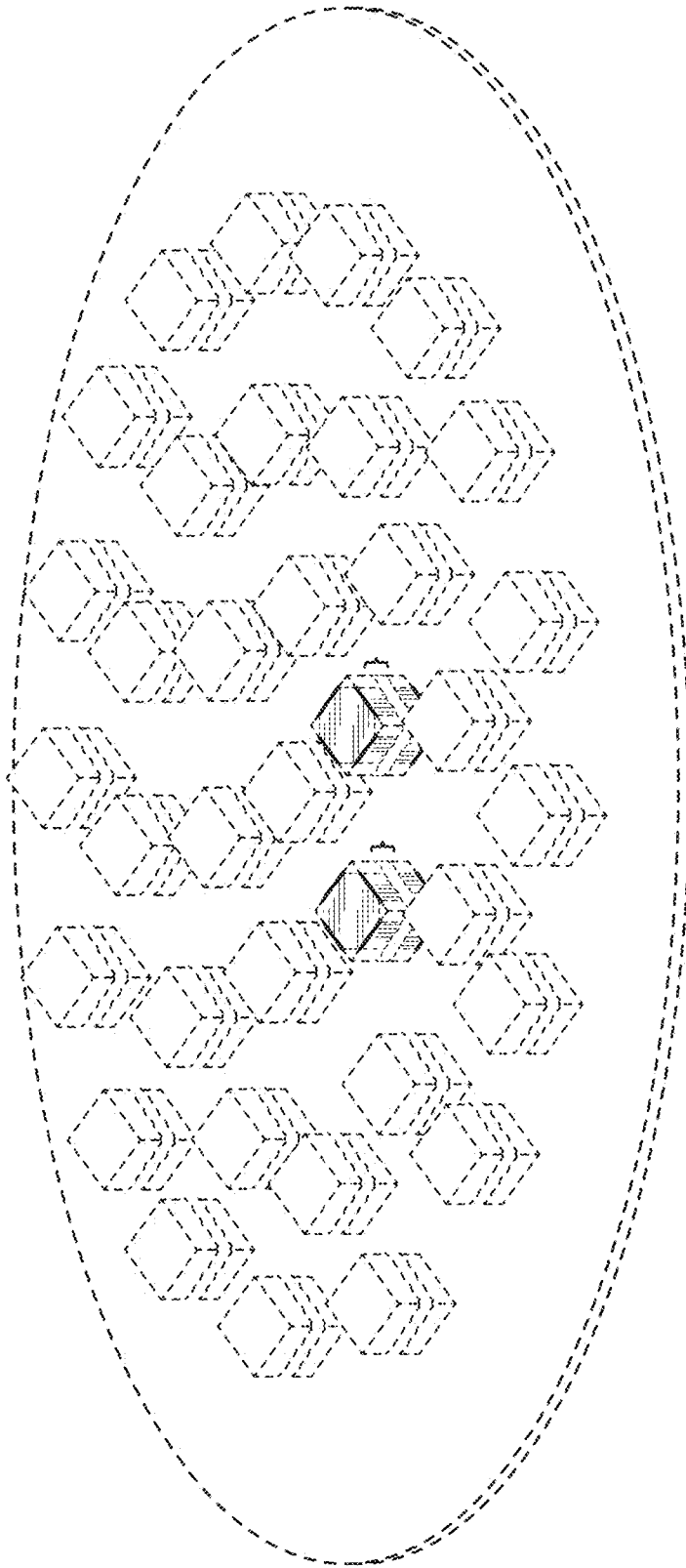


FIG. 15

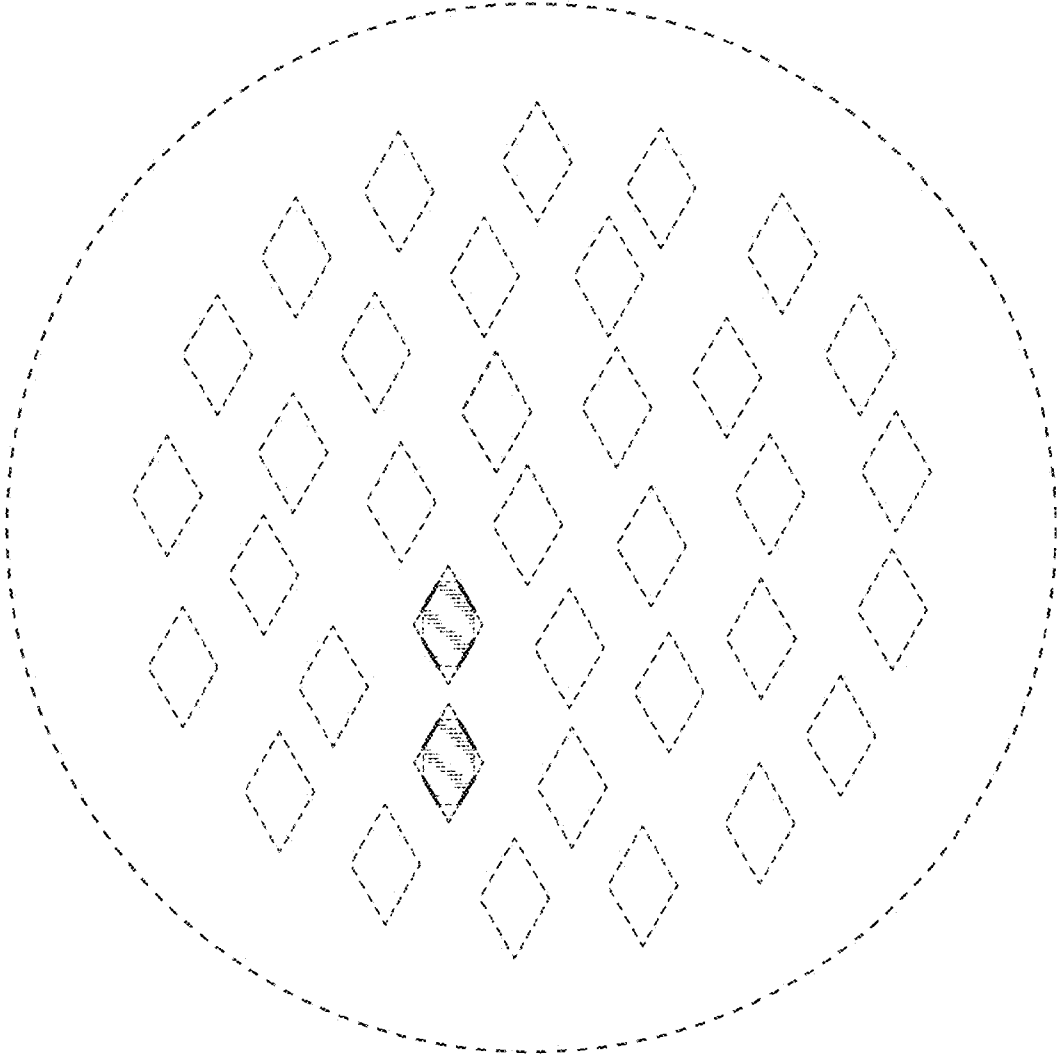


FIG. 16

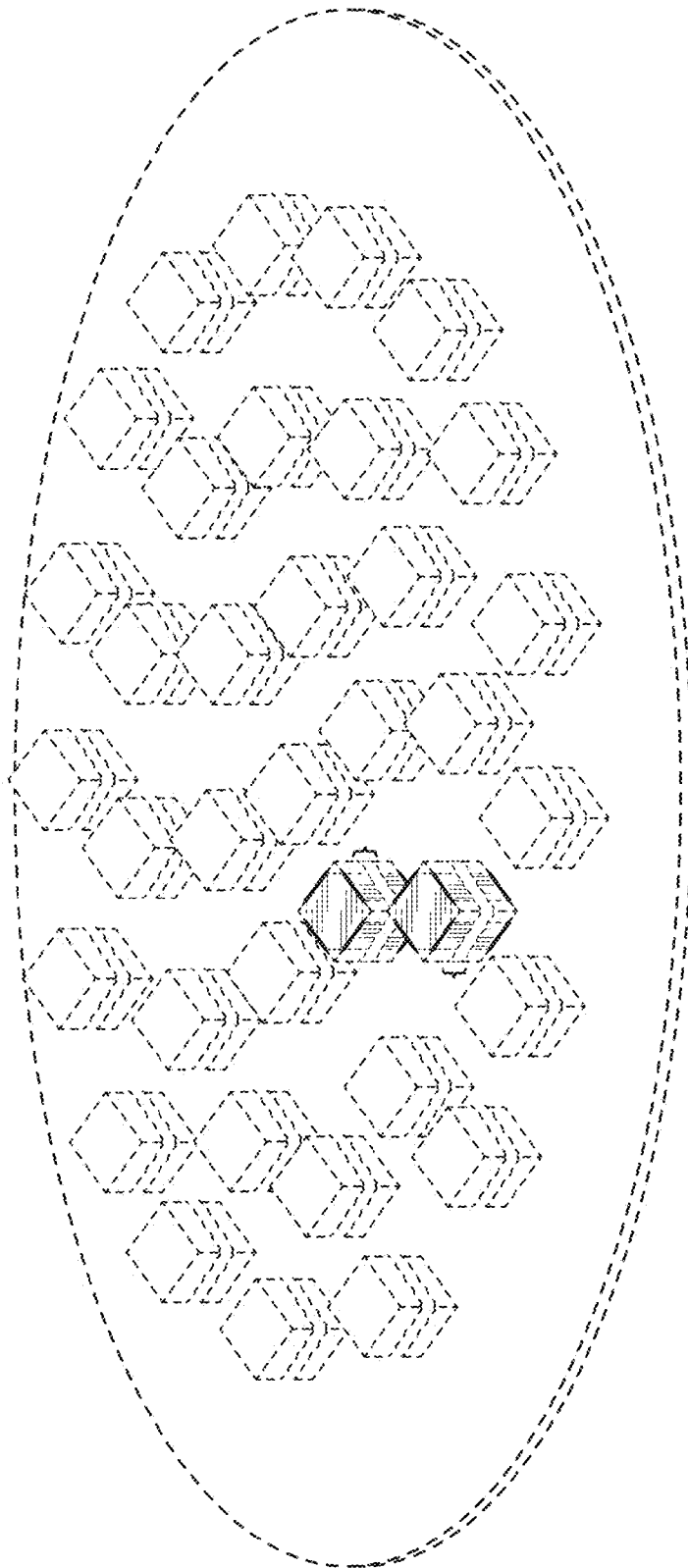


FIG. 17

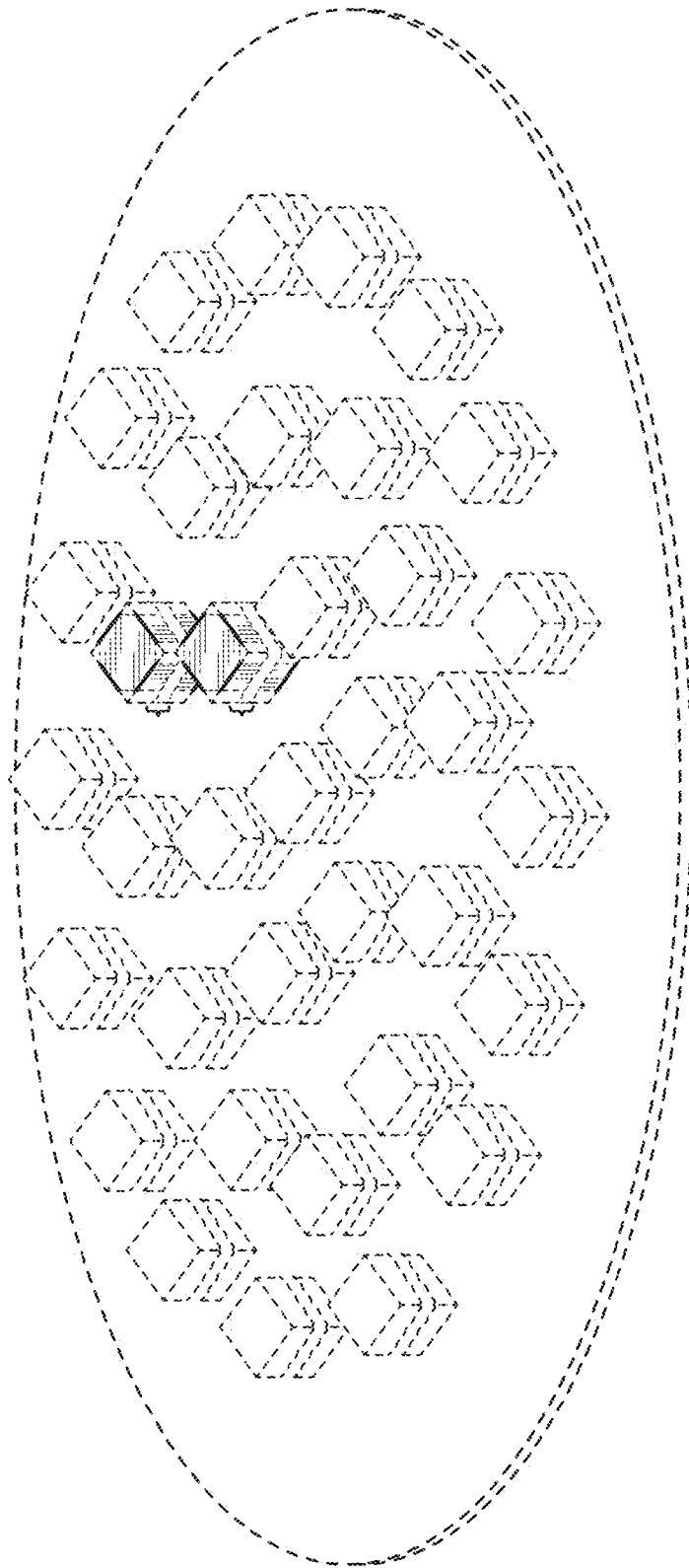


FIG. 18